10/660,054

Application No.: 10/660,054 Amendment Dated: February 16, 2009

Reply to Office Action of: December 26 2008

## **Amendments to the Claims**

This listing of claims will replace all prior versions and listings of claims in the application.

MAT-8260US1

## **Listing of Claims:**

1. - 36. (Cancelled)

37. (Previously Presented) A clad board for forming circuitry, the clad board being manufactured by:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

wherein said clad board comprises:

a fiber sheet included in the pre-preg sheet, the fiber sheet comprising a nonwoven fabric and a resin material impregnated into the fiber sheet, the resin material comprising at least one of a thermoplastic resin and a thermosetting resin having a semi-cured portion, the fiber sheet having a top surface and a bottom surface; and

a resin layer formed smoothly on both the top surface and the bottom surface of the fiber sheet, the resin layer being made of material identical to the resin material; and

wherein the fiber sheet comprises:

10/660,054

Amendment Dated:

February 16, 2009

Reply to Office Action of: December 26 2008

an inside layer having two faces and two surface layers, one of which surface layers is disposed on each face of the inside layer;

MAT-8260US1

and

wherein the density of the non-woven fabric in the inside layer is lower than the density of the non-woven fabric in each of the surface layers.

38. - 39. (Cancelled)

40. (Previously Presented) The clad board of claim 37, wherein the fiber sheet has a density ranging from 700 kg/m³ to 1000 kg/m³.

41. - 58. (Cancelled)

59. (Previously Presented) The clad board of claim 37,

wherein the fiber sheet has a hole formed therein, said clad board further comprising a conductive paste filling the hole of the fiber sheet, the conductive paste comprising non-spherical-shaped conductive particles.

60. - 75. (Cancelled)

76. (Currently Amended) A core board for a clad board for forming circuitry, the core board comprising:

a fiber sheet;

the fiber sheet comprising a non-woven fabric and a resin material impregnated into the fiber sheet, the resin material comprising at least one of a thermoplastic resin and a thermoplastic resin having a semi-cured portion, the fiber sheet having a top surface and a bottom surface;

and

a resin layer formed on both the top surface and the bottom surface of the fiber sheet, the resin layer being made of material identical to the resin material;

10/660,054

Amendment Dated:

February 16, 2009

Reply to Office Action of: December 26 2008

wherein the fiber sheet comprises:

an inside layer having two faces and two surface layers, one which surface layers is disposed on each face of the inside layer; and

MAT-8260US1

wherein the density of the non-woven fabric in the inside layer is lower than the density of the non-woven fabric in each if each of the surface layers.

## 77. - 83. (Cancelled)

- 84. (Previously Presented) The core board of claim 76, wherein the fiber sheet has a hole formed therein, said core board further comprising a conductive paste filling the hole of the fiber sheet, the conductive paste comprising nonspherical-shaped conductive particles.
- 85. (Previously Presented) The core board of claim 76, wherein the fiber sheet has a density ranging from 700 kg/m<sup>3</sup> to 1000 kg/m<sup>3</sup>.
- 86. (Previously Presented) The clad board of claim 37, wherein the resin material impregnated into the fiber sheet comprises the thermosetting resin having a semi-cured portion.
- (Previously Presented) The core board of claim 76, wherein the resin 87. material impregnated into the fiber sheet comprises the thermosetting resin having a semi-cured portion.

## 88. - 95. (Cancelled)

- 96. (Previously Presented) The clad board of claim 37, wherein the impregnated resin comprises 51 weight% to 54 weight% of the pre-preg sheet.
- (Previously Presented) The core board of claim 76, wherein the impregnated resin comprises 51 weight% to 54 weight% of the pre-preg sheet.
- (Previously Presented) The clad board of claim 37, wherein the non-98. woven fabric is an aramid fiber non-woven fabric.

10/660,054

Amendment Dated:

February 16, 2009

Reply to Office Action of: December 26 2008

99. (Previously Presented) The clad board of claim 98, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m³ and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m3.

MAT-8260US1

- 100. (Previously Presented) The clad board of claim 37, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m³ and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m<sup>3</sup>.
- 101. (Previously Presented) The core board of claim 76, wherein the nonwoven fabric is an aramid fiber non-woven fabric.
- 102. (Previously Presented) The core board of claim 101, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m³ and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m3.
- (Previously Presented) The core board of claim 76, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m³ and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m<sup>3</sup>.
- (Previously Presented) The clad board according to claim 37, wherein the inside layer and the two surface layers include a common resin material and a common non-woven fabric.
- (Previously Presented) The clad board according to claim 37, wherein the fiber sheet includes a further inside layer, identical in material to the two surface layers, positioned between the inside layer and one of the two surface layers, and having a density lower than a density of either of the two surface layers.